

N - CHANNEL ENHANCEMENT MODE POWER MOS TRANSISTOR

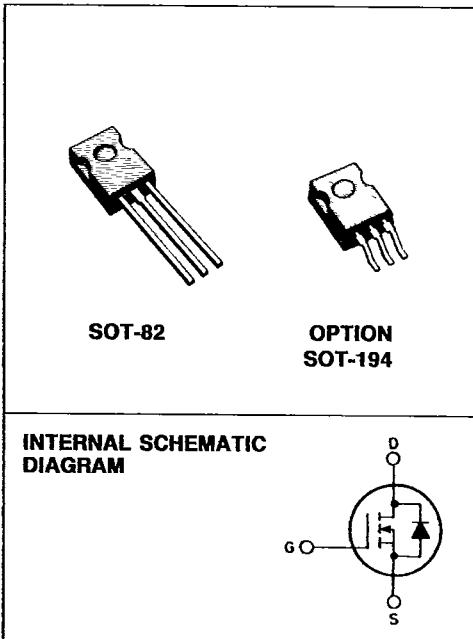
TYPE	V _{DSS}	R _{DS(on)}	I _D
SGSP230	450 V	3 Ω	2.5 A

- HIGH SPEED SWITCHING APPLICATIONS
- HIGH VOLTAGE - 450V FOR OFF-LINE SMPS
- ULTRA FAST SWITCHING FOR OPERATION AT > 100KHz
- EASY DRIVE FOR REDUCED COST AND SIZE

INDUSTRIAL APPLICATIONS:

- SWITCHING POWER SUPPLIES
- MOTOR CONTROLS

N - channel enhancement mode POWER MOS field effect transistor. Easy drive and very fast switching times make this POWER MOS transistor ideal for high speed switching applications. Typical applications include switching power supplies, uninterruptible power supplies and motor speed control.


ABSOLUTE MAXIMUM RATINGS

V _{DS}	Drain-source voltage (V _{GS} =0)	450	V
V _{DGR}	Drain-gate voltage (R _{GS} =20 KΩ)	450	V
V _{GS}	Gate-source voltage	±20	V
I _D	Drain current (cont.) at T _c =25°C	2.5	A
I _D	Drain current (cont.) at T _c =100°C	1.5	A
I _{DM} (*)	Drain current (pulsed)	10	A
I _{DLM} (*)	Drain inductive current, clamped	10	A
P _{tot}	Total dissipation at T _c < 25°C	50	W
	Derating factor	0.4	W/°C
T _{stg}	Storage temperature	-65 to 150	°C
T _j	Max. operating junction temperature	150	°C

(*) Pulse width limited by safe operating area

THERMAL DATA

R_{thj} - case	Thermal resistance junction-case	max	2.5	$^{\circ}\text{C}/\text{W}$
T_L	Maximum lead temperature for soldering purpose		275	$^{\circ}\text{C}$

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ELECTRICAL CHARACTERISTICS ($T_{case} = 25^{\circ}\text{C}$ unless otherwise specified)

Parameters	Test Conditions	Min.	Typ.	Max.	Unit
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OFF

$V_{(BR)DSS}$	Drain-source breakdown voltage	$I_D = 250 \mu\text{A}$	$V_{GS} = 0$	450			V
I_{DSS}	Zero gate voltage drain current ($V_{GS} = 0$)	$V_{DS} = \text{Max Rating}$			250	μA	
I_{GSS}	Gate-body leakage current ($V_{DS} = 0$)	$V_{DS} = \text{Max Rating} \times 0.8$	$T_c = 125^{\circ}\text{C}$	1000	μA		

ON (*)

$V_{GS(\text{th})}$	Gate threshold voltage	$V_{DS} = V_{GS}$	$I_D = 250 \mu\text{A}$	2		4	V
$R_{DS(on)}$	Static drain-source on resistance	$V_{GS} = 10 \text{ V}$	$I_D = 1.2 \text{ A}$			3	Ω
		$V_{GS} = 10 \text{ V}$	$I_D = 1.2 \text{ A}$	$T_c = 100^{\circ}\text{C}$		6	Ω

DYNAMIC

g_{fs}	Forward transconductance	$V_{DS} = 25 \text{ V}$	$I_D = 1.2 \text{ A}$	0.8			mho
C_{iss} C_{oss} C_{rss}	Input capacitance Output capacitance Reverse transfer capacitance	$V_{DS} = 25 \text{ V}$ $V_{GS} = 0$	$f = 1 \text{ MHz}$		340	450 95 50	pF pF pF

SWITCHING

$t_d(\text{on})$	Turn-on time	$V_{DD} = 225 \text{ V}$	$I_D = 1.2 \text{ A}$		10	15	ns
t_r	Rise time	$V_i = 10 \text{ V}$	$R_i = 4.7 \Omega$		25	35	ns
$t_d(\text{off})$	Turn-off delay time				55	70	ns
t_f	Fall time	(see test circuit)			25	35	ns

ELECTRICAL CHARACTERISTICS (Continued)

T-39-11

Parameters	Test Conditions	Min.	Typ.	Max.	Unit
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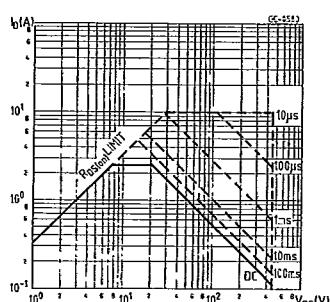
SOURCE DRAIN DIODE

I_{SD}	Source-drain current			2.5	A
I_{SDM} (*)	Source-drain current (pulsed)			10	A
V_{SD}	Forward on voltage	$I_{SD} = 2.5 \text{ A}$	$V_{GS} = 0$	1.2	V
t_{rr}	Reverse recovery time	$I_{SD} = 2.5 \text{ A}$	$V_{GS} = 0$	340	ns

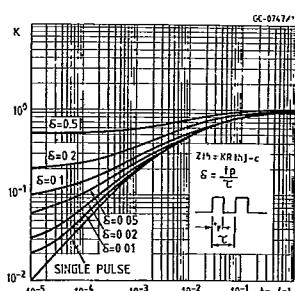
(*) Pulsed: Pulse duration = 300 μs , duty cycle 1.5%

(*) Pulse width limited by safe operating area

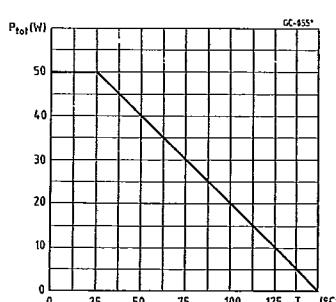
Safe operating areas



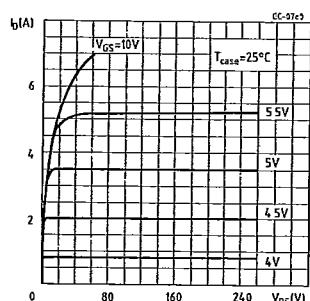
Thermal impedance



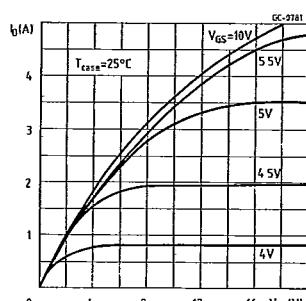
Derating curve



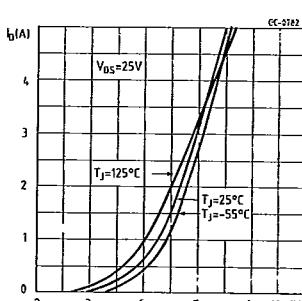
Output characteristics



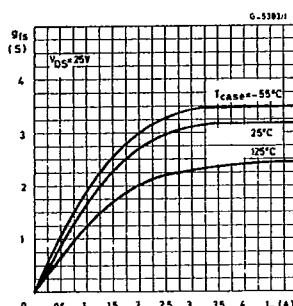
Output characteristics



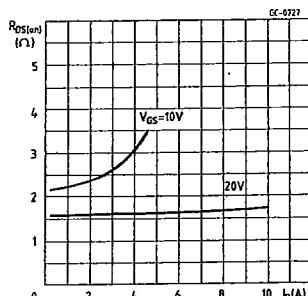
Transfer characteristics



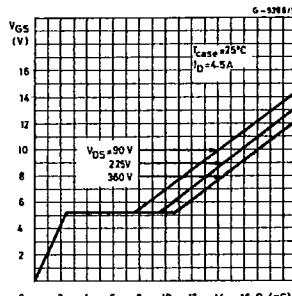
Transconductance



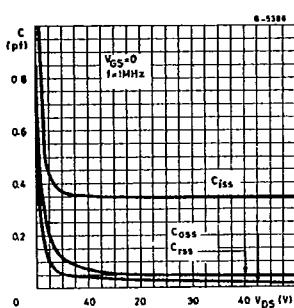
Static drain-source on resistance



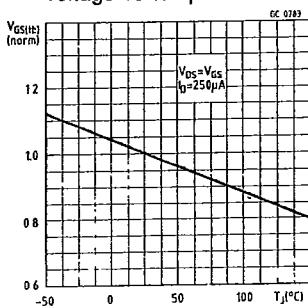
Gate charge vs gate-source voltage



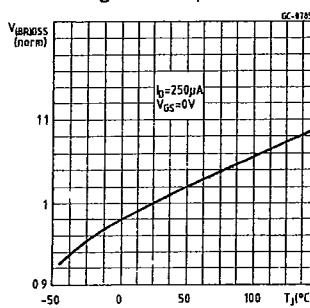
Capacitance variation



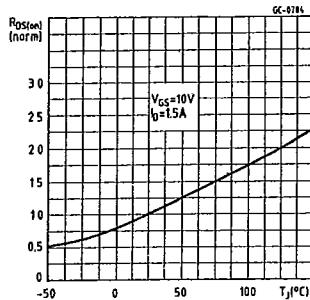
Normalized gate threshold voltage vs temperature



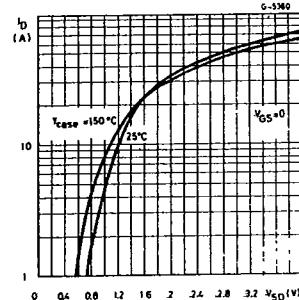
Normalized breakdown voltage vs temperature



Normalized on resistance vs temperature

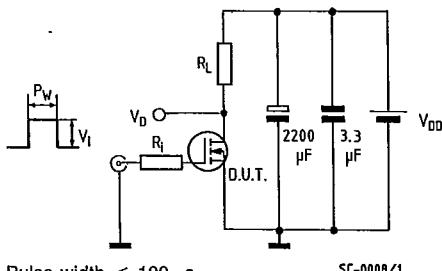


Source-drain diode forward characteristics

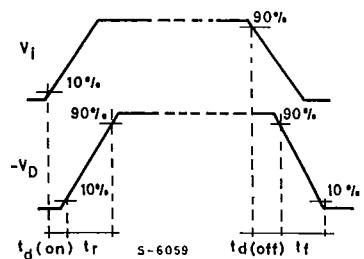


S G S-THOMSON

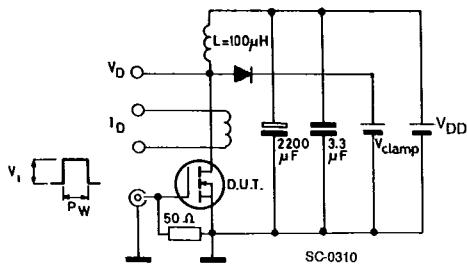
Switching times test circuit for resistive load



Switching time waveforms for resistive load

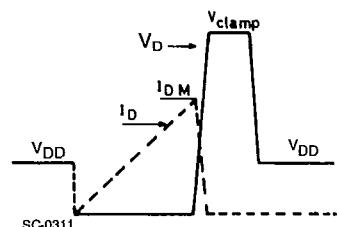


Clamped inductive load test circuit

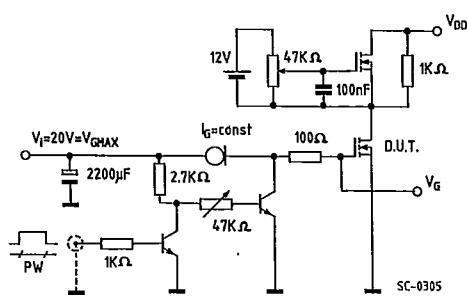


$V_1 = 12 \text{ V}$ - Pulse width: adjusted to obtain specified I_{DM} , $V_{\text{clamp}} = 0.75 V_{(\text{BR}) \text{ DSS}}$.

Clamped inductive waveforms



Gate charge test circuit

PW adjusted to obtain required V_G Body-drain diode t_{rr} measurement
Jedec test circuit